



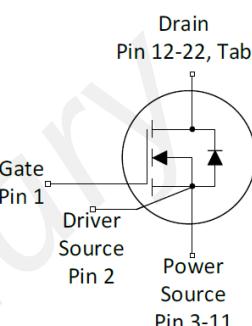
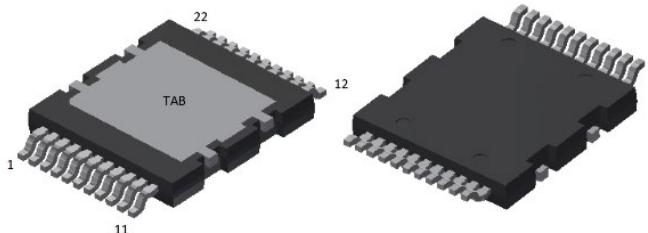
P3M07008PQ SiC MOS N-Channel Enhancement Mode

V_{RRM} = 750 V
 I_D = 208 A
 $I_D(100^\circ\text{C})$ = 147 A
 $R_{DS(on)}$ = 8 mΩ

SiC MOS P3M07008PQ N-Channel Enhancement Mode

Features

- High Blocking Voltage with Low On-Resistance
- High-Frequency Operation
- Ultra-Small Q_{gd}
- 100% UIS tested



Benefits

- Improve System Efficiency
- Increase Power Density
- Reduce Heat Sink Requirements
- Reduction of System Cost

PQPAK-LF-22

Gate	1
Kelvin Source	2
Power Source	3-11
Drain	TAB (12-22)

Applications

- Solar Inverters
- EV Battery Chargers
- High Voltage DC/DC Converters
- Switch Mode Power Supplies



Order Information

Part Number	Package	Marking
P3M07008PQ	PQPAK-LF-22	P3M07008PQ



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1. Maximum Ratings

At $T_J = 25^\circ\text{C}$, unless specified otherwise

Parameter	Symbol	Value	Unit	Test Conditions
Drain - Source Voltage	$V_{DS\max}$	750	V	$V_{GS} = 0\text{V}$ $I_D = 100\mu\text{A}$
Gate - Source Voltage (dynamic)	$V_{GS\max}$	-8 / +22	V	AC ($f > 1 \text{ Hz}$)
		-10 / +25		$t_p \leq 20\text{ns}$, dutycycle $\leq 1\%$
Gate - Source Voltage(static) turn-on gate voltage turn-off gate voltage	$V_{GS,\text{on}}$ $V_{GS,\text{off}}$	+15 / +18 -3	V	Static
Continuous Drain Current	I_D	208	A	$V_{GS} = 18\text{V}$ $T_C = 25^\circ\text{C}$
		147		$V_{GS} = 18\text{V}$ $T_C = 100^\circ\text{C}$
Pulsed Drain Current	$I_{D(\text{pulse})}$	700	A	$PW \leq 10\mu\text{s}$, Duty cycle $\leq 1\%$
Power Dissipation	P_D	789	W	
Operating Junction	T_J	-55 To +150	°C	
Storage Temperature	T_{stg}	-55 To +175	°C	
Solder Temperature	T_L	245	°C	



2. Electrical Characteristics

At $T_J = 25^\circ\text{C}$, unless specified otherwise

Parameter	Symbol	Value			Unit	Test Conditions
		Min.	Typ.	Max.		
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	750	/	/	V	$V_{\text{GS}} = 0\text{V}$ $I_D = 2.5\text{mA}$
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	2.0	2.7	/	V	(tested after 30ms pulse at $V_{\text{GS}} = 18\text{V}$) $V_{\text{DS}} = V_{\text{GS}}$ $I_D = 20\text{mA}$ $T_J = 25^\circ\text{C}$
		/	1.9	/	V	$V_{\text{DS}} = V_{\text{GS}}$ $I_D = 20\text{mA}$ $T_J = 175^\circ\text{C}$
Reverse Bias Drain Current	I_{DSS}	/	5	250	μA	$V_{\text{GS}} = 0\text{V}$ $V_{\text{DS}} = 750\text{V}$
Gate-Source Leakage Current	I_{GSS}	/	5	250	nA	$V_{\text{GS}} = 18\text{V}$ $V_{\text{DS}} = 0\text{V}$
Drain-Source On-State Resistance	$R_{\text{DS}(\text{on})}$	/	8	12	$\text{m}\Omega$	$V_{\text{GS}} = 18\text{V}$ $I_D = 75\text{A}$ $T_J = 25^\circ\text{C}$
		/	11	/		$V_{\text{GS}} = 18\text{V}$ $I_D = 75\text{A}$ $T_J = 175^\circ\text{C}$
Trans conductance	g_{fs}	/	48	/	S	$V_{\text{DS}} = 20\text{V}$ $I_{\text{DS}} = 75\text{A}$ $T_J = 25^\circ\text{C}$
		/	45	/		$V_{\text{DS}} = 20\text{V}$ $I_{\text{DS}} = 75\text{A}$ $T_J = 175^\circ\text{C}$



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Parameter	Symbol	Value			Unit	Test Conditions
		Min.	Typ.	Max.		
Input Capacitance	C_{iss}	/	7698	/	pF	$V_{GS} = 0V$ $V_{DS} = 500V$ $f = 500kHz$ $V_{AC} = 25mV$
Output Capacitance	C_{oss}	/	516	/		
Reverse Transfer Capacitance	C_{rss}	/	40	/		
Coss Stored Energy	E_{oss}	/	112	/	μJ	
Turn-on Energy	E_{on}	/	664	/	μJ	$V_{DS} = 500V$ $V_{GS} = -3/18V$ $I_D = 75A$ $R_G = 1\Omega$
Turn-off Energy	E_{off}	/	194	/		
Turn-On Delay Time	$t_{d(on)}$	/	24.8	/		$V_{DS} = 500V$ $V_{GS} = -3/18V$ $I_D = 75A$ $R_G = 1\Omega$
Rise Time	t_r	/	39	/		
Turn-Off Delay Time	$t_{d(off)}$	/	82	/		
Fall Time	t_f	/	8.6	/		
Internal Gate Resistance	$R_{G(int)}$	/	1.5	/	Ω	$f = 1MHz$ $V_{AC} = 25mV$
Gate to Source Charge	Q_{gs}	/	245	/	nC	$V_{DS} = 500V$ $I_{DS} = 75A$ $V_{GS} = -3/18V$ $I_G = 20mA$
Gate to Drain Charge	Q_{gd}	/	85	/		
Total Gate Charge	Q_g	/	407	/		



3. Reverse Diode Characteristics

At $T_J = 25^\circ\text{C}$, unless specified otherwise

Parameter	Symbol	Value		Unit	Test Conditions
		Typ.	Max.		
Diode Forward Voltage	V_{SD}	5.2	/	V	$V_{GS} = -3\text{V}$ $I_{SD} = 38\text{A}$ $T_J = 25^\circ\text{C}$
		4.6	/	V	$V_{GS} = -3\text{V}$ $I_{SD} = 38\text{A}$ $T_J = 175^\circ\text{C}$
Continuous Diode Forward Current	I_S	68	/	A	$V_{GS} = -3\text{V}$
Reverse Recover Time	t_{rr}	21	/	ns	$V_{GS} = -3/18\text{V}$
Reverse Recovery Charge	Q_{rr}	926	/	nC	$I_{SD} = 75\text{A}$ $V_R = 500\text{V}$ $d_i/d_t = 4200\text{A}/\mu\text{s}$
Peak Reverse Recovery Current	I_{rrm}	74	/	A	$T_J = 25^\circ\text{C}$

4. Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction to Case	$R_{\theta JC}$	0.19	°C/W



5. Typical Performance

At $T_J = 25^\circ\text{C}$, unless specified otherwise

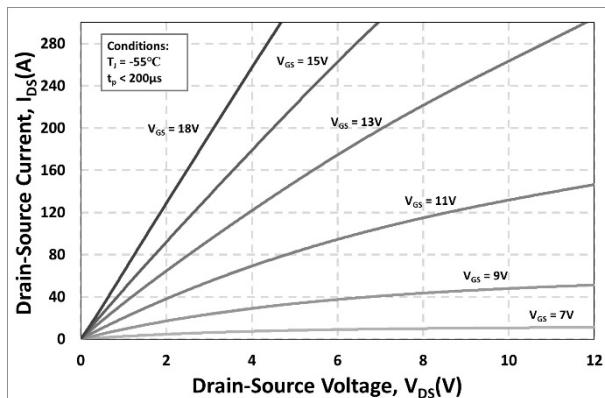


Figure 1. Output Characteristics $T_J = -55^\circ\text{C}$

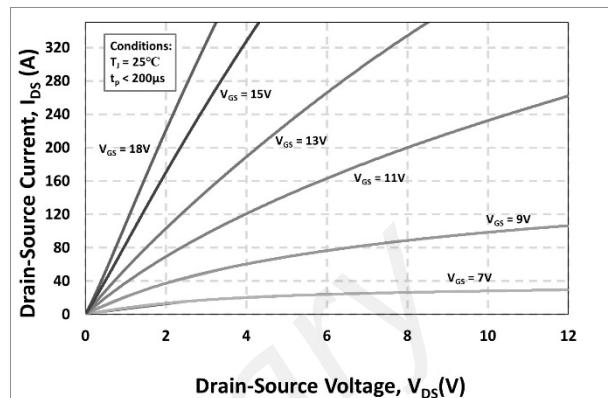


Figure 2. Output Characteristics $T_J = 25^\circ\text{C}$

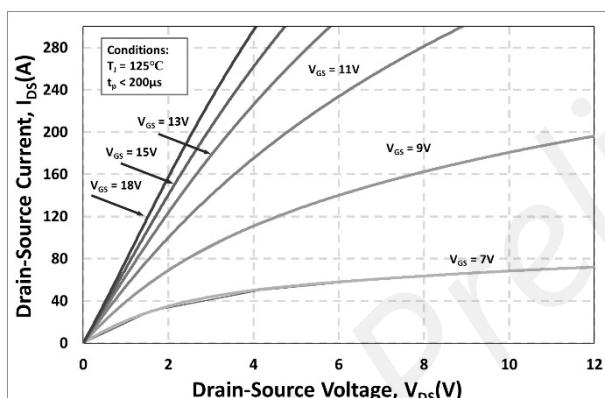


Figure 3. Output Characteristics $T_J = 125^\circ\text{C}$

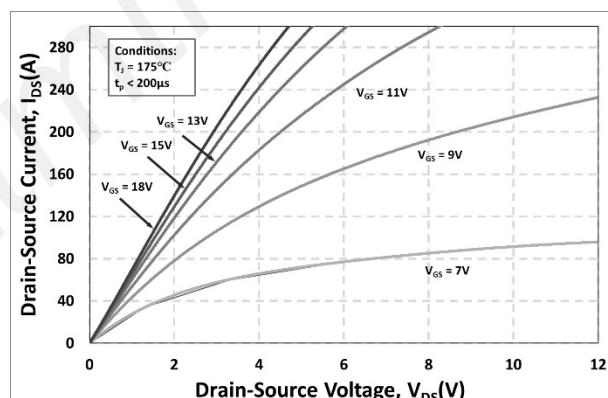


Figure 4. Output Characteristics $T_J = 175^\circ\text{C}$

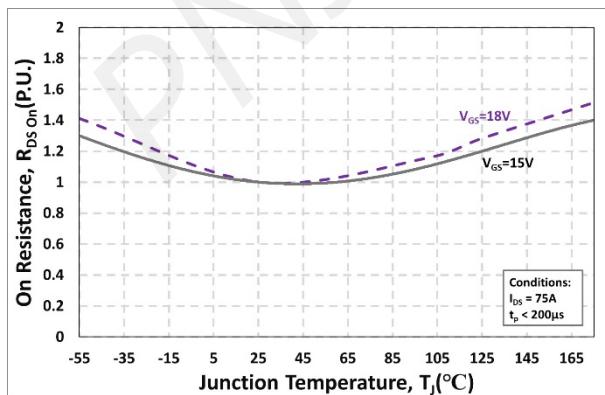


Figure 5. Normalized On-Resistance vs. Temperature

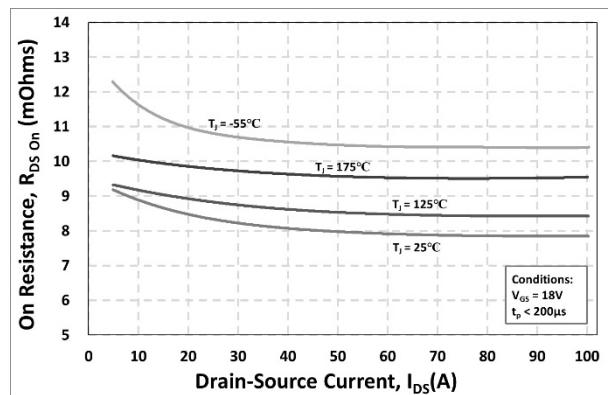


Figure 6. On-Resistance vs. Drain Current Various Temperatures



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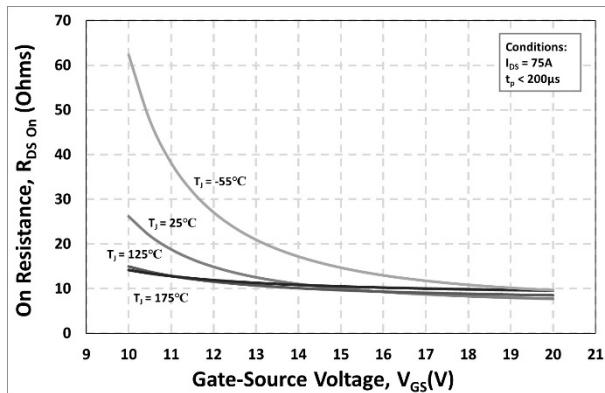


Figure 7. On-Resistance vs. Gate-Source Voltage

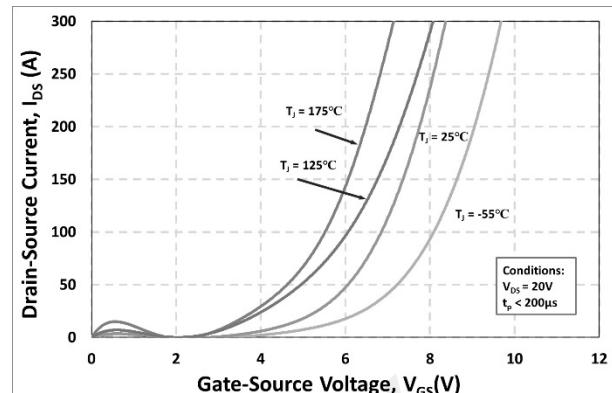


Figure 8. Transfer Characteristic for Various Junction Temperatures

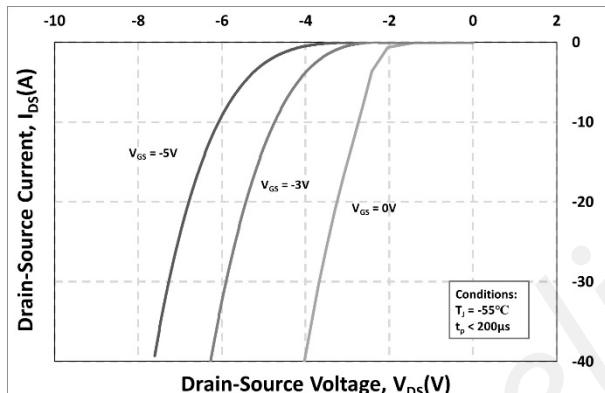


Figure 9. Body Diode Characteristic at $-55^{\circ}C$

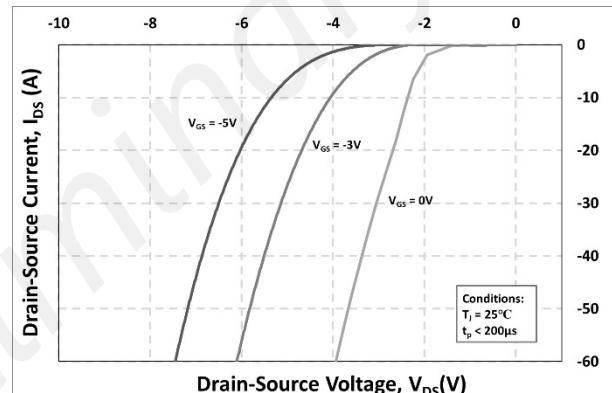


Figure 10. Body Diode Characteristic at $25^{\circ}C$

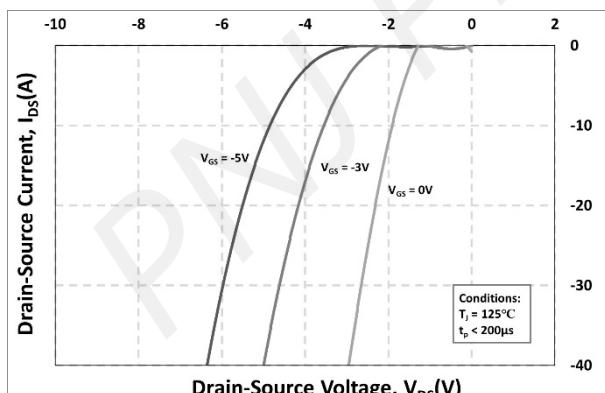


Figure 11. Body Diode Characteristic at $125^{\circ}C$

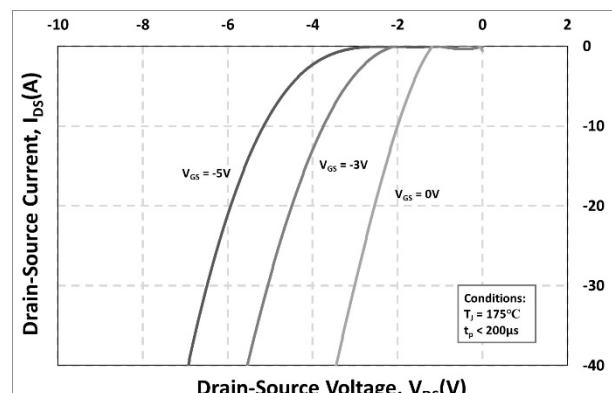


Figure 12. Body Diode Characteristic at $175^{\circ}C$



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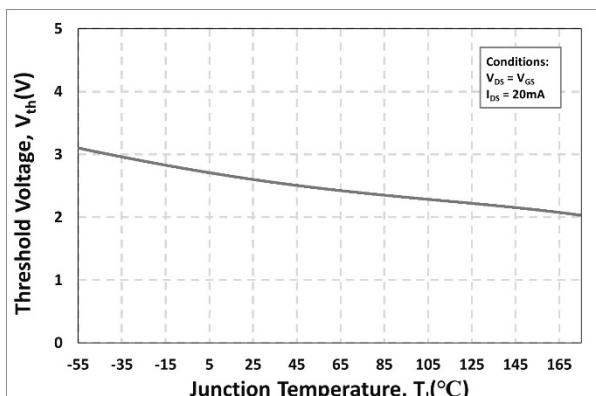


Figure 13. Threshold Voltage vs. Temperature

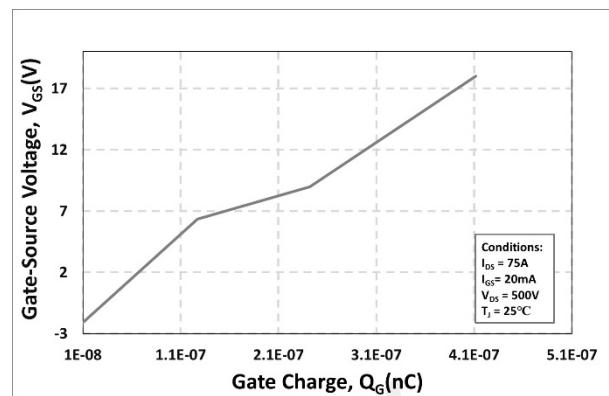


Figure 14. Gate Charge Characteristics

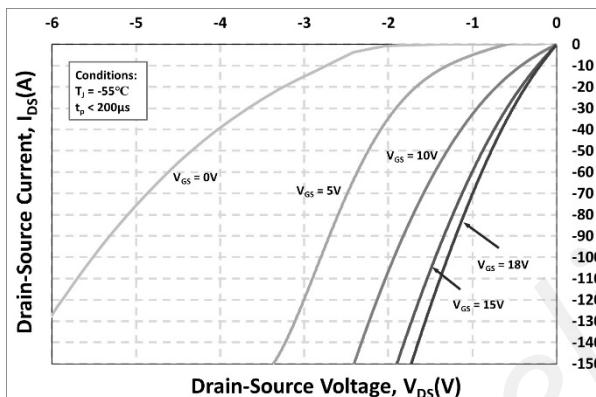


Figure 15. 3rd Quadrant Characteristic at -55°C

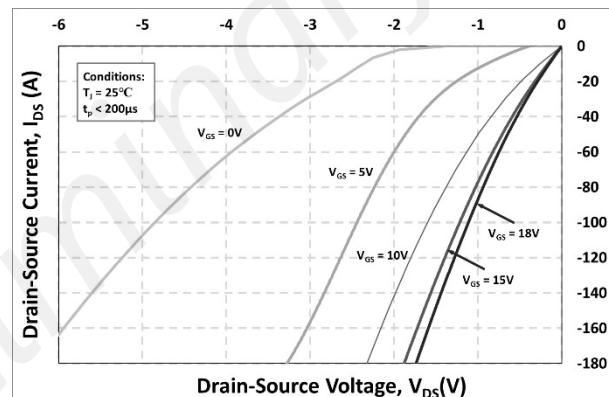


Figure 16. 3rd Quadrant Characteristic at 25°C

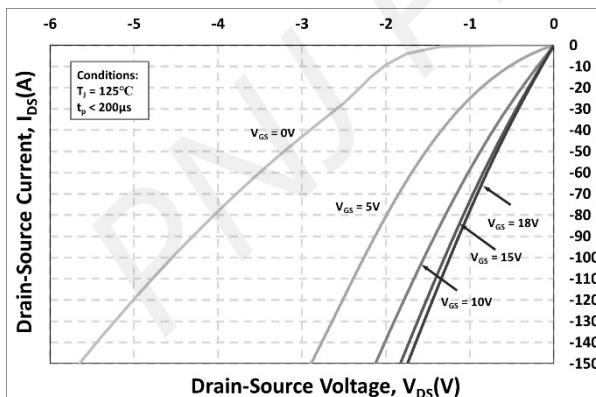


Figure 17. 3rd Quadrant Characteristic at 125°C

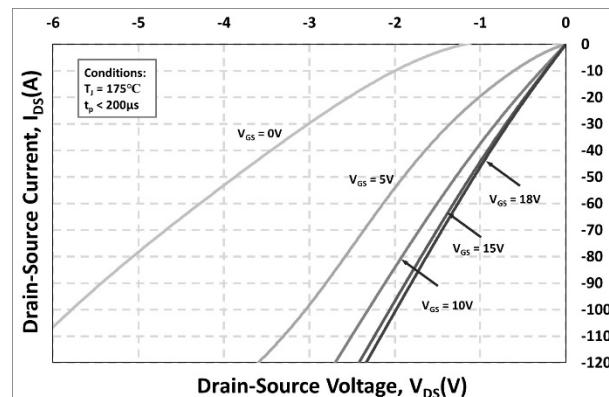


Figure 18. 3rd Quadrant Characteristic at 175°C



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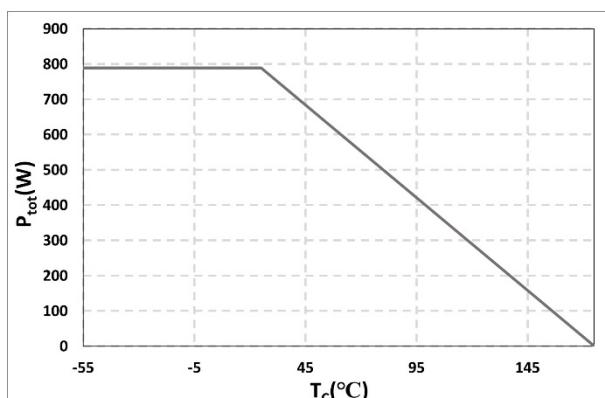


Figure 19. Maximum Power Dissipation Derating vs. Case Temperature

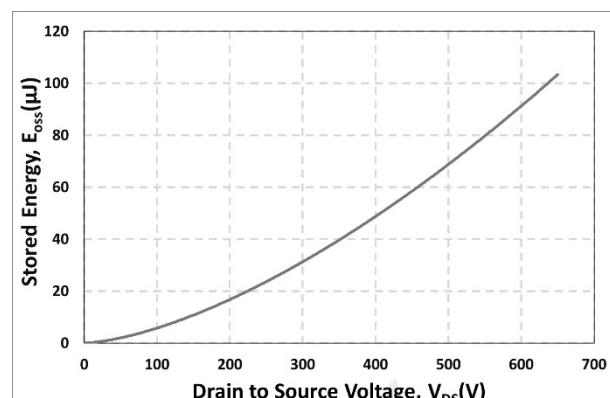


Figure 20. Output Capacitor Stored Energy

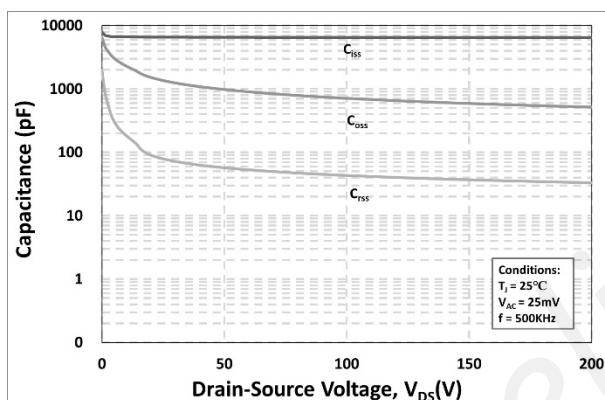


Figure 21. Capacitances vs. Drain-Source Voltage (0 - 200V)

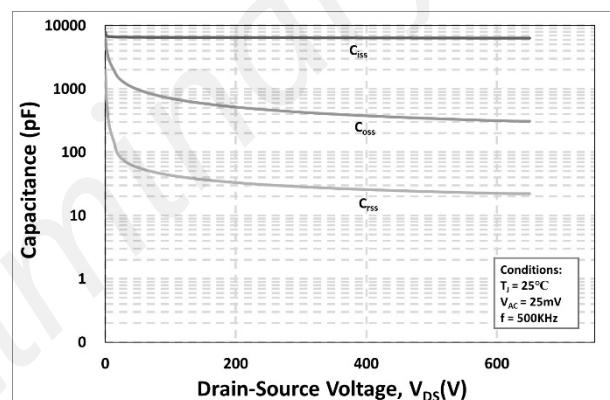
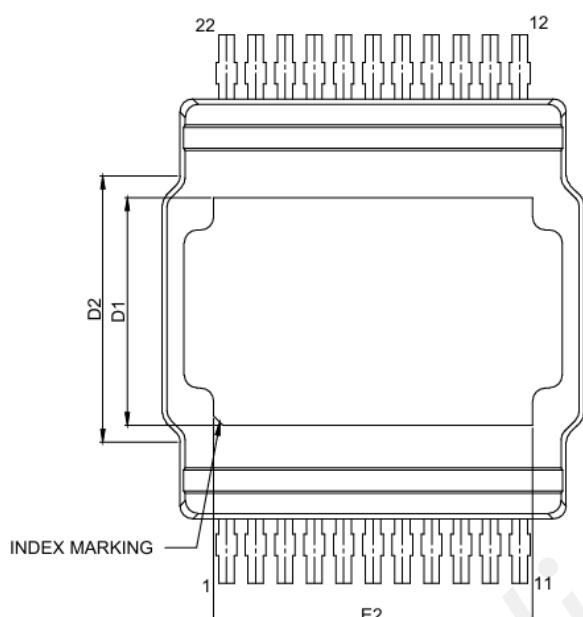


Figure 22. Capacitances vs. Drain-Source Voltage (0 - 750V)

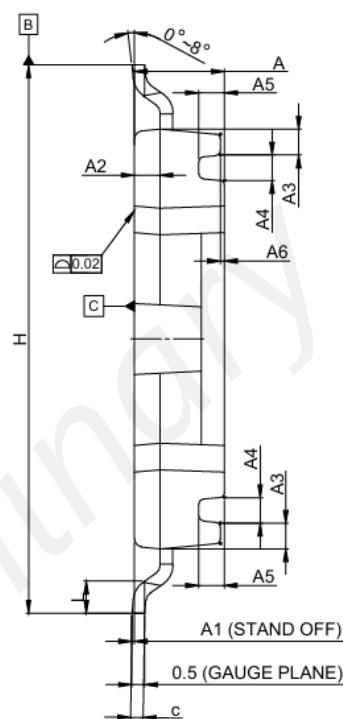


6. Package Outlines

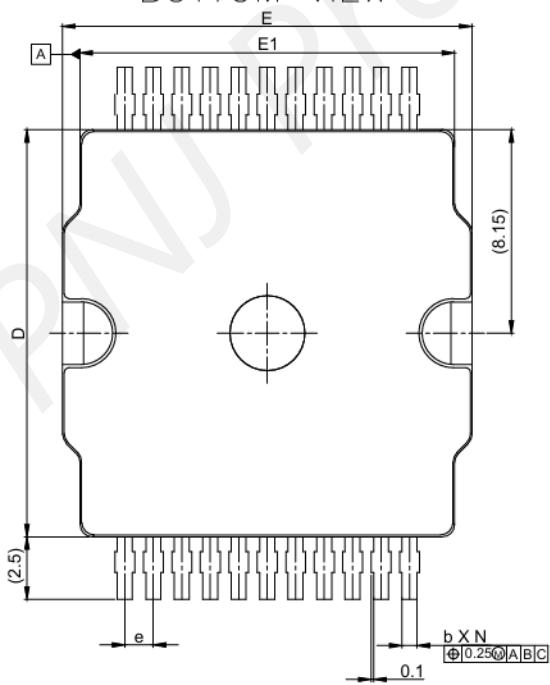
TOP VIEW



SIDE VIEW



BOTTOM VIEW



SYMBOL	Common		
	DIMENSIONS MILLIMETER		
	MIN.	NOM.	MAX.
A	3.40	3.50	3.60
A1	0.00	0.09	0.15
A2	0.90	1.00	1.10
A3	0.90	1.00	1.10
A4	0.88	0.98	1.08
A5	0.90	1.00	1.10
A6	0.05	0.15	0.25
b	0.50	0.60	0.70
c	0.40	0.50	0.60
D	16.20	16.30	16.40
D1	8.79	8.84	8.89
D2	10.23	10.33	10.43
E	16.30	16.40	16.50
E1	14.90	15.00	15.10
E2	12.30	12.40	12.50
e		1.14	
L	1.14	1.24	1.34
H	21.20	21.30	21.40
N		22	

Drawing and Dimensions



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